ASU Southwest Advanced Prototyping Hub
Arizona State University

| 2026 SWAP Hub Annual Meeting & Advanced Packaging Workshop<br>Building Partnerships to Accelerate the Next Generation of Microelectronics & Advanced Packaging | |
|---|---|
| **Agenda (all times PDT)** | |
| **Day 1: Monday October 26, 2026<br>Mountain America Stadium, ASU, Tempe, AZ<br>500 E Veterans Way, Tempe, AZ 85287** | |
| **8:00 - 9:00 AM** | **Registration** |
| **9:00 - 9:05 AM** | **Welcome**<br>**Sally C. Morton**, Executive Vice President, ASU Knowledge Enterprise |
| **Session 1: Hub Updates** | |
| **9:05 - 9:35 AM** | **Overview, Roadmap and Sustainability**<br>**Jason Conrad**, ASU SWAP Hub COO |
| **9:35 - 10:05 AM** | **Capabilities, Project Overviews and Transitions**<br>**Krishnendu Chakrabarty**, ASU SWAP Hub CTO |
| **10:05 - 10:20 AM** | **Workforce Development and Successes**<br>**Binil Starly**, School Director and Professor, School of Manufacturing Systems and Networks, ASU |
| **10:20 - 10:50 AM** | **Break** |
| **Session 2: Project Presentations, Session Chair Krishnendu Chakrabarty** | |
| **10:50 - 12:30 PM** | **Integrated RF GaN Technology to Support Next Generation Wireless Systems, Jennifer Kitchen**, ASU |
| | **SMART - Scalable Modular Architecture for RF Transceivers, Phaneendra Bikkina**, Alphacore |
| | **SLEAC - Spaceborne Low-Energy AI Computing, Matthew Marinella**, ASU |
| | **Multi-MHz, High Density, Ultra-fast RADAR Power Converter, Raja Ayyanar**, ASU, **Francis Kub**, ME Commons Commercial Leap Ahead Technical Area Lead, NRL |
| | **ARC-V Secure Processor: Bruce Babb**, General Dynamics |
| **12:30 - 1:30 PM** | **Lunch** |
| **Session 3: Capabilities Deep Dive & Industry/USG Lab Partnerships, Session Chair Krishnendu Chakrabarty** | |
| **1:30 - 3:15 PM** | **Heterogenous Integration, Christopher Bailey**, Professor, School of Electrical, Computer and Energy Engineering, ASU, **Ken Dean**, Senior Manager, Advanced Semiconductor Technologies, Sandia National Laboratories |
| | **Rad-hard/Extreme Environment Reliability, Hugh Barnaby**, Professor, School of Electrical, Computer and Energy Engineering, ASU, **Ken Dean**, Senior Manager, Advanced Semiconductor Technologies, Sandia National Laboratories |
| | **Trust and Assured Infrastructure for Nanotechnology (TRAIN), Jim Plusquellic**, President and CEO, IC-Safety |
| | **Power and RF Electronics, Trevor Thornton**, Professor, School of Electrical, Computer and Energy Engineering, ASU |
| | **Metrology and Characterization, Umberto Celano**, Associate Professor, School of Electrical, Computer and Energy Engineering, ASU |
| | **Circuits, Architectures and Test, Sule Ozev**, Professor, School of Electrical, Computer and Energy Engineering, ASU |
| | **Rad-hard CMOS+X Integration, Matt Marinella**, Associate Professor, School of Electrical, Computer and Energy Engineering, ASU |
| **3:15 - 3:30 PM** | **IP and Technology Licensing**<br>**Januk Aggarwal**, Director, Intellectual Property - Physical Sciences, Skysong Innovations |
| **3:30 - 4:00 PM** | **Break** |
| **Session 4: Local Ecosystem** | |
| **4:00 - 5:00 PM** | **Fireside Chat: "From Regional Strength to National Impact: Arizona's Microelectronics Future"**<br>**Kate Gallego**, Mayor of Phoenix, **Dave McCann**, Senior Vice President and Chief of Staff for Business Units, Amkor Technology, **Krishna Muralidharan** Professor, Materials Science and Engineering, University of Arizona**, Lisa Depew**, Program Director, Corporate University Research, Intel, **Tom Beckley**, Senior VP, Strategic Technology Programs, Cadence<br>**Moderator: Dean Kyle Squires**, Senior Vice Provost of Engineering, Computing and Technology |
| **5:00 - 6:00 PM** | **Venture Capital Panel: "From Prototypes to Portfolios: Investing in the Future of Microelectronics"**<br>**Jeb H. Flemming**, Founder and CTO, 3D Glass Solutions, **Blake Roberts**, Director, Cyber Security & Emerging Technologies, Lockheed Martin, **Rachna Dayal**, Founder & Managing Partner, Sugati Ventures, **Caroline (Cece) Sambuco,** Investor In-Q-Tel, **Andy Lombard**, Founder and CEO TESORO VC<br>**Moderator: Saverio Fazzari**, Engineering Fellow for Microelectronics, Booz Allen Hamilton |
| **6:00 - 6:05 PM** | **Closing Remarks and Adjourn (Day 1)** |
| **6:05 - 8:30 PM** | **Reception at the Arboretum, located adjacent to the Mountain America Stadium** |

ASU Southwest Advanced Prototyping Hub
Arizona State University

ASU Southwest Advanced Prototyping Hub
Arizona State University

| 2026 SWAP Hub Annual Meeting & Advanced Packaging Workshop<br>Building Partnerships to Accelerate the Next Generation of Microelectronics & Advanced Packaging | |
|---|---|
| **Agenda (all times PDT)** | |
| **Day 2: Tuesday October 27, 2026<br>Mountain America Stadium, ASU, Tempe, AZ<br>500 E Veterans Way, Tempe, AZ 85287** | |
| **7:00 - 8:25 AM** | **Continental Breakfast and Registration** |
| **8:25 - 8:30 AM** | **Opening Remarks** |
| **Session 5: Government Updates, Session Chair Krishnendu Chakrabarty** | |
| **8:30 - 9:00 AM** | **Keynote #1**<br>**The Future of DoW Microelectronics, Eric Makara**, Microelectronics Program Manager, OUSW (R&E), OASW (CT) |
| **9:00 - 9:30 AM** | **Keynote #2**<br>**The Race to Field: Turning Microelectronics Innovation into Warfighter Advantage, Nicholas Martin**, Director, Defense Microelectronics Activity |
| **9:30 - 10:00 AM** | **AI Hardware**<br>**Clare Thiem**, Principal Electronics Engineer, AFRL & **Gunasekaran Seetharam**, NRL, ME Commons AI Hardware CTEA Co-Leads |
| **10:00- 10:30 AM** | **Break** |
| **Session 6: Industry Mini-Keynotes, Session Chair Vish Viswanathan** | |
| **10:30 - 12:30 AM** | **Ravi Mahajan**, Fellow, Assembly & Test Tech Pathfinding, Intel |
| | **Chandra Raj**, Deputy General Manager, Viasat |
| | **Roberto Verezo**, Technical Leader, Autonomy and Artificial Intelligence, General Atomics |
| | **Hardware Solutions for SWaP-C Constrained Systems, Jonathan Comeau**, Chief Technology Officer, Otava RF |
| | **Physical Artificial Intelligence for RF Design, Vikas Shilimkar**, Cofounder DesignX |
| | **A Photodefinable Hardmask to Enable Ultra-Fine Pitch RDL, Thomas McCune**, Director of Advanced Packaging R&D. NanoPattern Technologies, Inc |
| **12:30 - 1:30 PM** | **Lunch** |
| **Session 7: DIB Presentations & Quantum Panel, Session Chair Robert Robinson** | |
| **1:30 - 2:30 PM** | **Xiaosu (Cathy) Zheng**, Manager, MMIC, RFIC & T/R Modules Lockheed Martin |
| | **Onshoring Advanced Packaging at Northrop Grumman, David Shahin**, Senior Manager, Advanced Packaging, Northrop Grumman Microelectronics Center |
| | **Successfully Crossing the Last Five Yards of the Valley of Death, Mike Burkland**, Sr. Principal Systems Engineer, Raytheon Missile Systems |
| **Panel: "Opportunities in Quantum Technology"** | |
| **2:30 - 3:30 PM** | **Ali Torabi**, CEO, Lawrence Semiconductor, **Michael Fanto**, ME Commons Quantum Co-CTEA Lead, Senior Research Physicist AFRL/RITQ, **Jungsang Kim**, Multifunctional Integrated Systems Technology Group Lead, Duke University**, Daniel Lopez**, Chair and Professor, TCLAS The College - Division of Natural Sciences, ASU, **Alicia Magann**, Staff Scientist, Quantum Performance Laboratory, Sandia National Laboratories<br>**Moderator: Rick McCormick**, Special Advisor to the CTO, SWAP Hub Senior Scientist (Retired), Sandia National |
| **3:30 -3:50 PM** | **Break** |
| **Session 8: Funding Opportunities** | |
| **3:50 - 5:20 PM** | **Panel: "The Road to Funding Is Paved with Transition Opportunities"**<br>**Dev Palmer**, Consultant, Applied Research Institute, **Chris Bozada**, Senior Scientist, Air Force Research Laboratory, **Mike Holmes**, Managing Director, DARPA NGMM, **Carl McCants**, Principal Engineer, Intel Corporation, **Drew Trojanowski**, CEO, Southwest Mission Acceleration Center<br>**Moderator: Saverio Fazzari**, Engineering Fellow for Microelectronics, Booz Allen Hamilton |
| **5:20 - 5:25 PM** | **Closing Remarks and Adjourn (Day 2)** |
| **6:00 - 8:30 PM** | **MacroTechnology Works (MTW) Tour and Reception. Don't miss out, update your Registration at an additional cost.**<br>7700 S River Parkway, Tempe, AZ 85284 |

ASU Southwest Advanced Prototyping Hub
Arizona State University

Southwest Advanced Prototyping Hub
Arizona State University

| 2026 SWAP Hub Annual Meeting & Advanced Packaging Workshop<br>Building Partnerships to Accelerate the Next Generation of Microelectronics & Advanced Packaging | |
|---|---|
| **Agenda (all times PDT)** | |
| **Day 3: Wednesday October 28, 2026<br>Mountain America Stadium, ASU, Tempe, AZ<br>500 E Veterans Way, Tempe, AZ 85287** | |
| **7:15 - 8:25 AM** | **Continental Breakfast and Registration** |
| **8:25 - 8:30 AM** | **Opening Remarks** |
| **8:30 - 9:00 AM** | **Keynote #3**<br>**Tim Olson**, Founder & CEO, Deca Technologies |
| **9:00 - 9:30 AM** | **Invited Talk: From Chiplets to AI: New Horizons in Building Secure Hardware, Ankur Srivastava**, Director, Semiconductor Initiative and Innovation Professor, University of Maryland |
| **Session 9: Defense Labs and Tech Transition Perspectives, Session Chair Jason Conrad** | |
| **9:30 - 10:30 AM** | **Securing Next-Generation Microelectronics The RESHAPE Strategy, Michael Sinanis**, NSWC Crane, OASW, IBAS RESHAPE |
| | **Lab to Field: Advancing Microelectronics for Next-Generation RF Sensors, Kelson Chabak**, AFRL, Microelectronics Technical Area Lead |
| | **State-of-the-Art Heterogeneous Integrated Packaging (SHIP) Case Study: Transitioning Microelectronics for the Department of War, Brian Olson**, NSWC Crane, OUSW (R&E) Advanced Packaging Lead |
| **10:30- 11:00 AM** | **Break** |
| **Session 10: Design & Test** | |
| **11:00 - 12:15 AM** | **Panel: "From Chiplets to Systems: Advanced Packaging Design and Test"**<br>**Nilanjan Mukherjee**, VP Engineering, Tessent, Siemens Digital Industries, **John Carulli**, Director for Strategic Partner Development, Advantest, **Jonathan Mickschs**, Solutions Director, AE, Cadence, **Sankaran Menon**, AI/ML and DFX Architect/Engineer, Ericsson<br>**Moderator: Sule Ozev**, Professor, School of Electrical, Computer and Energy Engineering, ASU |
| **12:15- 1:15 PM** | **Lunch** |
| **Session 11: Roadmaps, Session Chair Ravi Mahajan** | |
| **1:15 - 1:45 PM** | **Packaging Roadmaps, Christopher Bailey**, Professor, School of Electrical, Computer and Energy Engineering, ASU |
| **Panel: "Keeping Cool as Integration Heats Up: Thermal Challenges in Advanced Packaging"** | |
| **1:45- 3:00 PM** | **Clay Pullins**, Senior Staff, Advanced Packaging Chief Engineer, Northrop Grumman Microelectronics Center, **Harsha Hakka**l, Senior Application Engineer Architect, Cadence, **Je-Young Chang**, Principal Engineer at Intel Corporation, Intel Corporation<br>**Moderator: Christopher Bailey**, Professor, School of Electrical, Computer and Energy Engineering, ASU |
| **3:00- 3:20 PM** | **Break** |
| **Session 12: Industry Partners, Session Chair Kevin Reinhart** | |
| **3:20 - 4:20 PM** | **Advanced Packaging to Achieve Spectrum Dominance at the Edge, Tony Trinh**, Senior Director, Advanced Concepts, Mercury Systems |
| | **Advanced Packaging Driving Spectrum Superiority, Kyle Holzer**, Senior RF Design Engineer, L3Harris |
| **4:20 - 4:30 PM** | **Closing Remarks and Adjourn (Day 3)** |

Southwest Advanced Prototyping Hub
Arizona State University